



September 14, 2023

Company name: TOKYO ELECTRON DEVICE LIMITED
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(TSE Prime Market, Stock Exchange Code: 2760)
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Announcement of Business Acquisition

TOKYO ELECTRON DEVICE LIMITED (the “Company”) hereby announces that the Company, at its Board of Directors’ meeting on September 14, 2023, resolved to acquire the wafer inspection system business (as a deemed resolution), a part of the business of Nippon Electro-Sensory Devices Corporation, as described below.

1. Purpose of Business Acquisition

The Company launched the wafer inspection system business in 2020 and has been engaged in sales activities mainly in Japan. The Company has decided to acquire this business, considering that in the semiconductor production system market, which is expected to continue to grow, the expansion of wafer inspection system and the enhancement of inspection technology, as well as the acceleration of overseas business development, will contribute to further business domain expansion and profitability improvement in the future.

2. Outline of Business Acquisition

(1) Details of the division to be acquired

Wafer inspection system business

(2) Operating results of division to be acquired

Not disclosed due to contractual obligations of confidentiality with the counterparty. The estimated increases in consolidated net sales, consolidated ordinary income, and net income attributable to owners of parent do not meet the disclosure criteria.

(3) Items and amounts of assets and liabilities of the division to be acquired

Not disclosed due to contractual obligations of confidentiality with the counterparty. The estimated increase in consolidated net assets does not meet the disclosure criteria.

(4) Acquisition price and payment method

The acquisition price was determined through negotiations with the counterparty of the business acquisition, taking into account the results of calculations by the Company and a third-party organization. However, due to contractual confidentiality obligations with the counterparty, the amount is undisclosed.

The payment method is cash settlement.

3. Overview of Counterparty

(1) Name	Nippon Electro-Sensory Devices Corporation	
(2) Location	Itachibori 2-5-12 Nishi-ku, Osaka	
(3) Job title and name of representative	CEO: Soichiro Rikimi	
(4) Description of business	Development, manufacture, and sale of industrial cameras and image-processing inspection system	
(5) Share capital	98,000 thousand yen	
(6) Date of establishment	November 10, 1975	
(7) Major shareholders and ownership ratios	Century Sogyo Co., Ltd.: 100%	
(8) Relationship between the Company and said company	Capital relationship	Not applicable
	Personnel relationship	
	Business relationship	
	Related party relationship	

4. Timetable

(1) Date of board resolution (deemed resolution)	September 14, 2023
(2) Date of contract	September 15, 2023 (scheduled)
(3) Date of business acquisition	October 2, 2023 (scheduled)

5. Outline of Accounting Procedures

This business acquisition falls under the category of “acquisition” under the Accounting Standards for Business Combinations and is expected to generate positive goodwill, but the impact on the Company’s business is expected to be minimal.

6. Future Outlook

The impact of this matter on the consolidated financial results for the fiscal year ending March 31, 2024 is expected to be immaterial. The Company will promptly announce any matters that should be disclosed in the future.

(Reference) Forecast of consolidated business results for current fiscal year (announced on April 27, 2023) and consolidated results for previous fiscal year

	Consolidated net sales	Consolidated ordinary income	Net income attributable to owners of parent
Forecast of consolidated financial results for current period (ending March 31, 2024)	Million yen 230,000	Million yen 12,000	Million yen 8,450
Consolidated results for previous period (ended March 31, 2023)	240,350	12,478	8,778